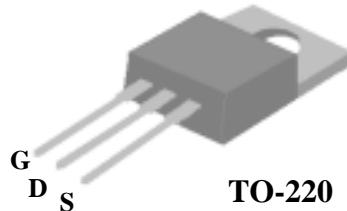




- ▼ Dynamic dv/dt Rating
- ▼ Repetitive Avalanche Rated
- ▼ Fast Switching
- ▼ Simple Drive Requirement

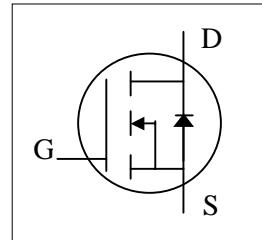


$BV_{DSS}$	400V
$R_{DS(ON)}$	1.0Ω
$I_D$	5.5A

## Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching , ruggedized device design , low on-resistance and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications. The device is suited for switch mode power supplies ,DC-AC converters and high current high speed switching circuits.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	400	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	5.5	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	3.5	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	23	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	74	W
	Linear Derating Factor	0.59	W/°C
$E_{AS}$	Single Pulse Avalanche Energy <sup>2</sup>	260	mJ
$I_{AR}$	Avalanche Current	5.5	A
$E_{AR}$	Repetitive Avalanche Energy	7	mJ
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-c}$	Thermal Resistance Junction-case	Max. 1.7	°C/W
$R_{thj-a}$	Thermal Resistance Junction-ambient	Max. 62	°C/W



## Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

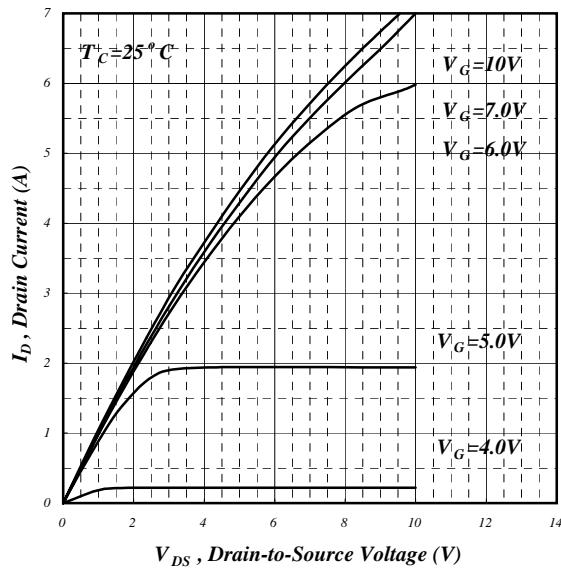
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	400	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	-	0.36	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=2.75\text{A}$	-	-	1	$\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	2	-	4	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=2.75\text{A}$	-	30	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current ( $T_j=25^\circ\text{C}$ )	$V_{\text{DS}}=400\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	10	$\mu\text{A}$
	Drain-Source Leakage Current ( $T_j=150^\circ\text{C}$ )	$V_{\text{DS}}=320\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}= \pm 30\text{V}$	-	-	$\pm 100$	$\text{nA}$
$Q_g$	Total Gate Charge <sup>3</sup>	$I_D=5.5\text{A}$	-	35	-	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=320\text{V}$	-	3.7	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=10\text{V}$	-	20	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time <sup>3</sup>	$V_{\text{DD}}=200\text{V}$	-	8	-	ns
$t_r$	Rise Time	$I_D=5.5\text{A}$	-	20	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	$R_G=10\Omega$ , $V_{\text{GS}}=10\text{V}$	-	47	-	ns
$t_f$	Fall Time	$R_D=36\Omega$	-	18	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	565	-	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=25\text{V}$	-	70	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	38	-	pF

## Source-Drain Diode

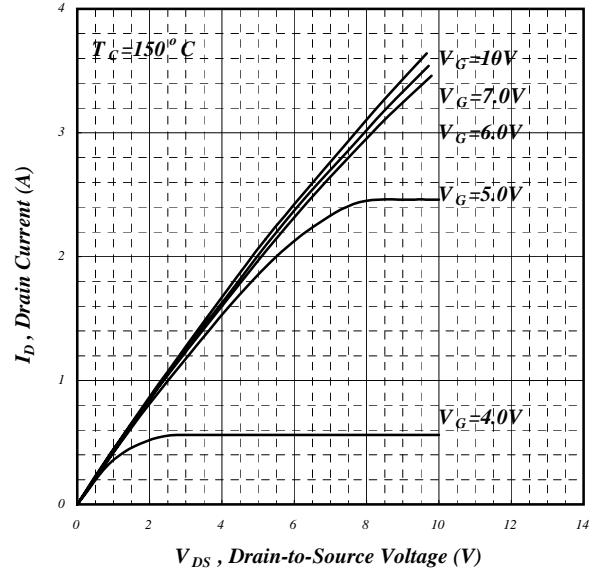
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$I_S$	Continuous Source Current ( Body Diode )	$V_D=V_G=0\text{V}$ , $V_S=1.5\text{V}$	-	-	5.5	A
$I_{\text{SM}}$	Pulsed Source Current ( Body Diode ) <sup>1</sup>		-	-	23	A
$V_{\text{SD}}$	Forward On Voltage <sup>3</sup>	$T_j=25^\circ\text{C}$ , $I_S=5.5\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	1.5	V

### Notes:

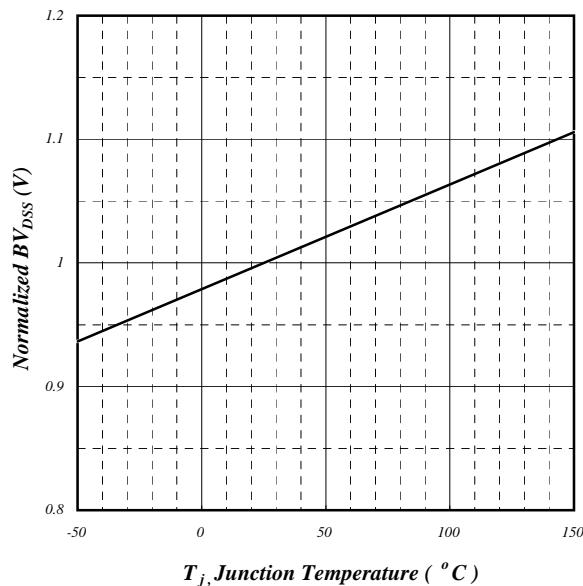
- 1.Pulse width limited by safe operating area.
- 2.Starting  $T_j=25^\circ\text{C}$  ,  $V_{\text{DD}}=50\text{V}$  ,  $L=15\text{mH}$  ,  $R_G=25\Omega$  ,  $I_{\text{AS}}=5.5\text{A}$ .
- 3.Pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .



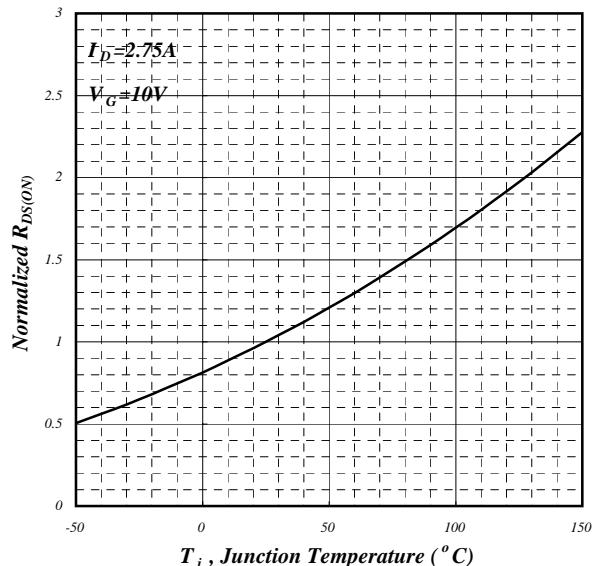
**Fig 1. Typical Output Characteristics**



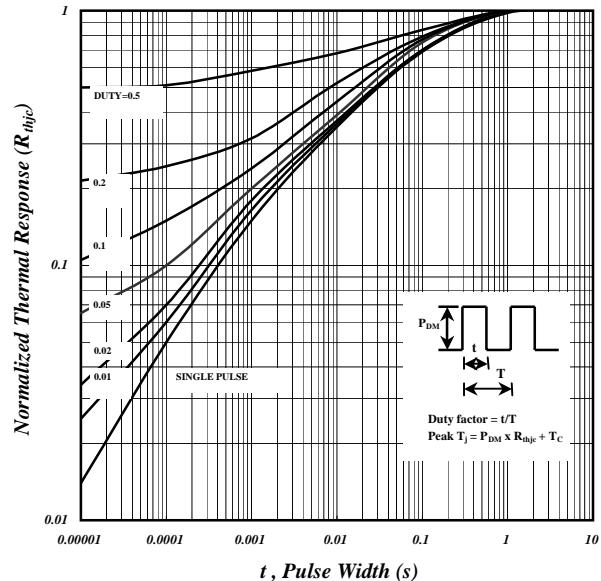
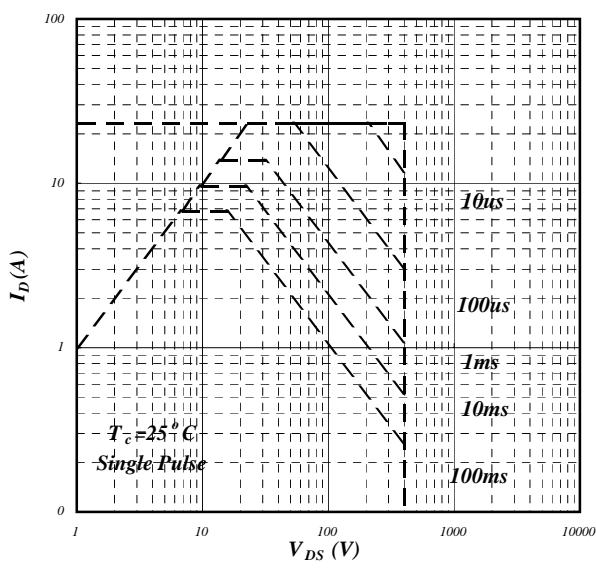
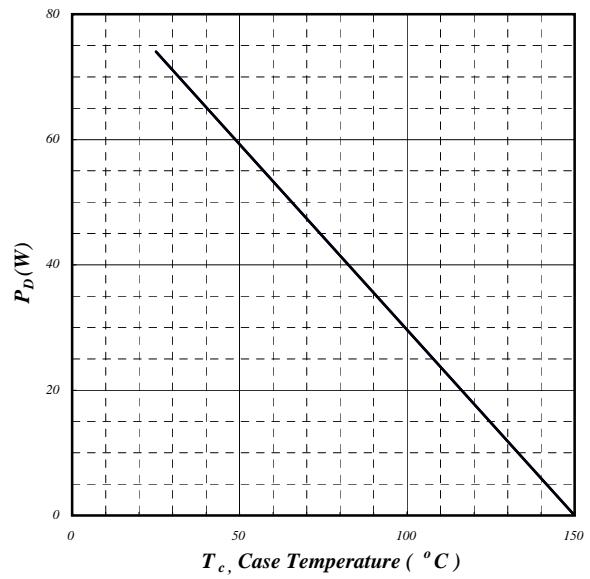
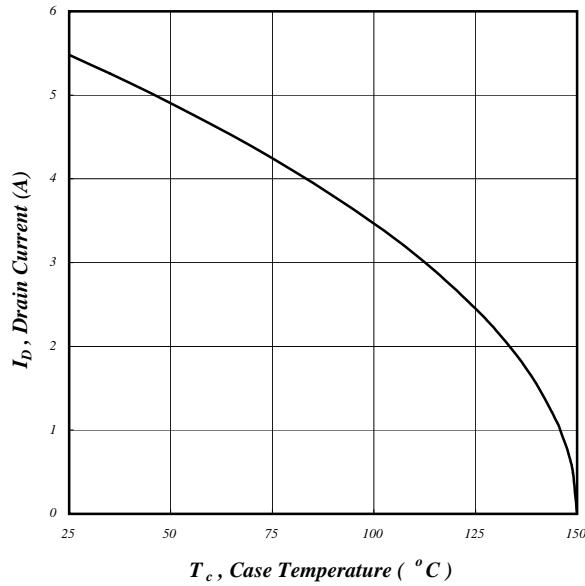
**Fig 2. Typical Output Characteristics**



**Fig 3. Normalized  $BV_{DSS}$  v.s. Junction Temperature**



**Fig 4. Normalized On-Resistance v.s. Junction Temperature**



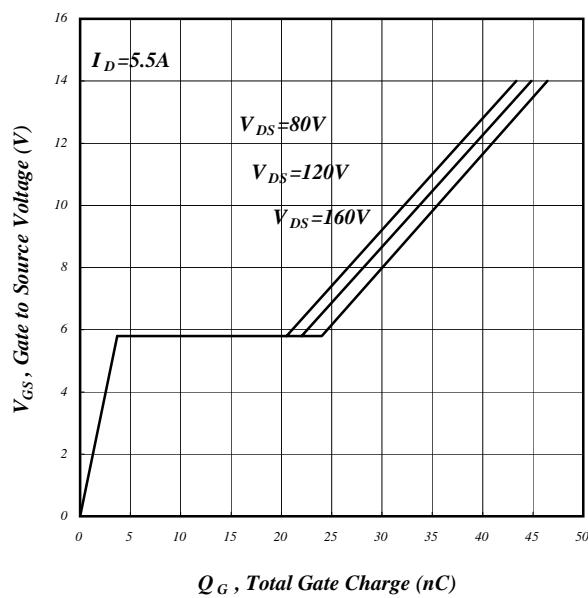


Fig 9. Gate Charge Characteristics

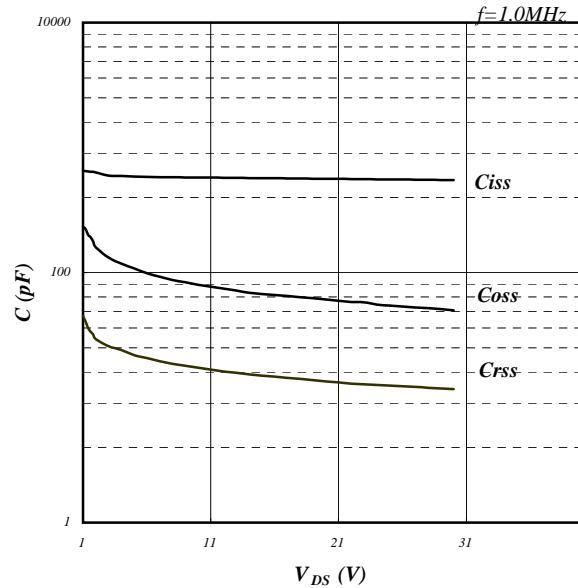


Fig 10. Typical Capacitance Characteristics

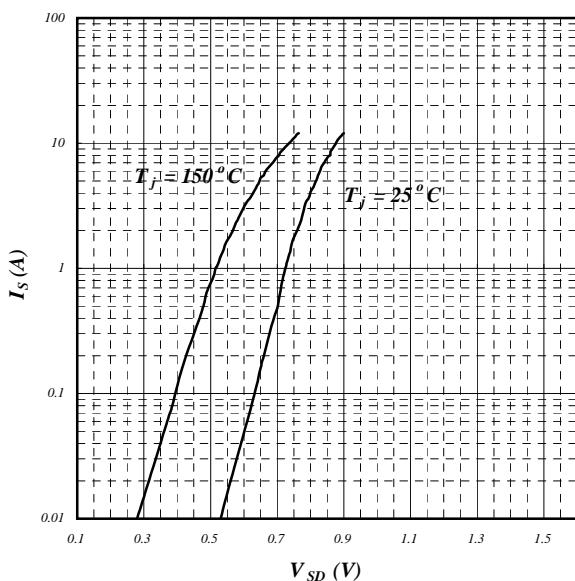


Fig 11. Forward Characteristic of Reverse Diode

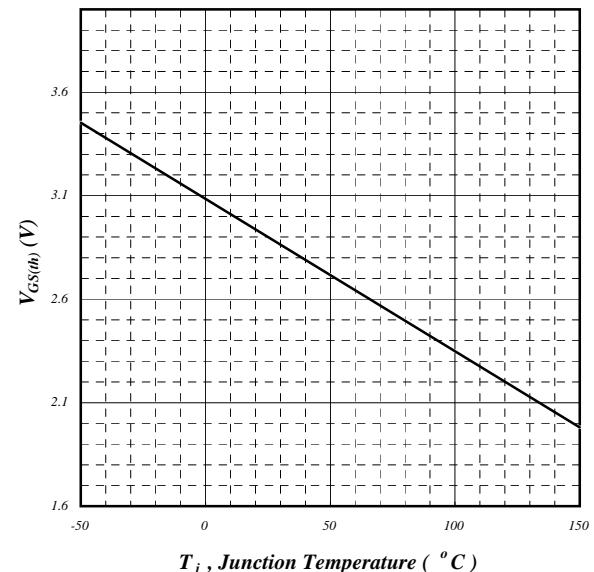
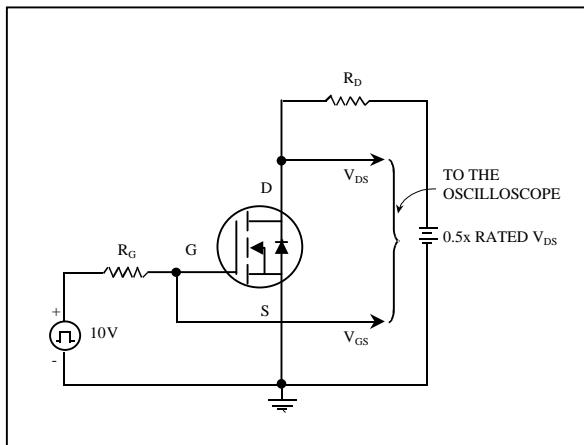
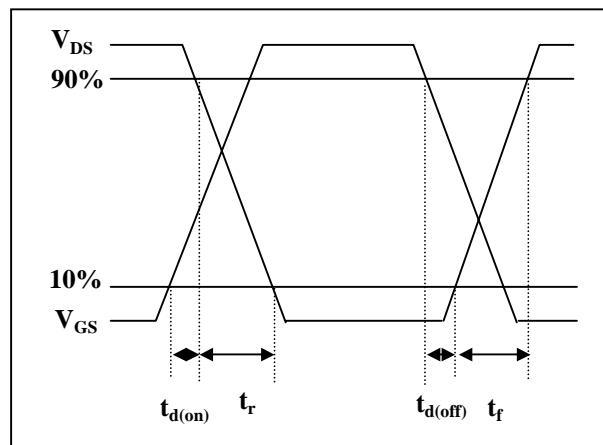


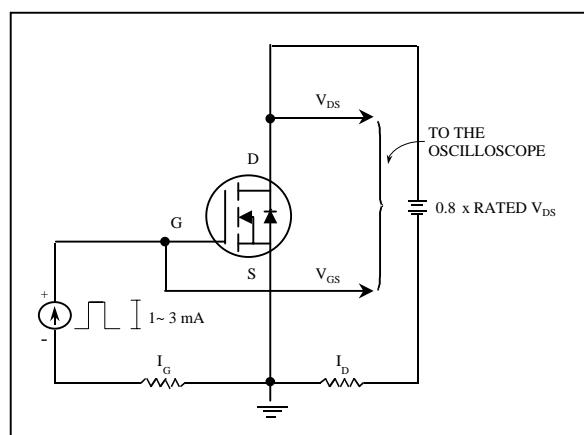
Fig 12. Gate Threshold Voltage v.s. Junction Temperature



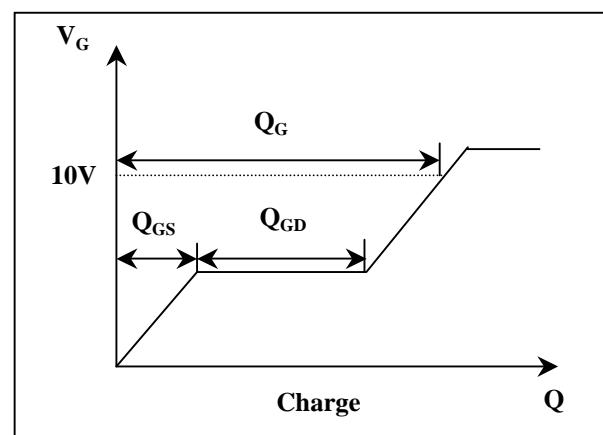
**Fig 13. Switching Time Circuit**



**Fig 14. Switching Time Waveform**



**Fig 15. Gate Charge Circuit**



**Fig 16. Gate Charge Waveform**